

NXP pushes car-to-X market with launch of new RoadLINK solution

June 12 2014

NXP Semiconductors today announced that the TEF510x, the second product from the RoadLINK range, is now available to automotive Original Equipment Manufacturers (OEMs) and Tier 1 suppliers for design-in. The TEF510x is a dual radio multi band RF transceiver for Car-to-X (C2X) applications. Supporting global C2X and Wi-Fi standards, the TEF510x provides OEMs with an optimized solution to meet 802.11p modem functionality on one chip. The chip has the flexibility to support global deployments and various system configurations.

The TEF510x RF transceiver meets Japanese 760Mz C2X requirements, US and European (5.9GHz) as well as Wi-Fi and DSRC (5.8GHz) specifications. It will be released for automotive production in 2015 and is expected to be available to consumers as early as 2016.

Together with the NXP/Cohda Wireless SAF510x baseband processor, powered by software defined radio technology, the RoadLINK chip provides fast, accurate and reliable communication to and from the vehicle. RoadLINK takes C2X communications to the next level by bringing safety-critical information to the driver significantly faster than current, conventional applications can.

Japanese-based company ALPS Electric is already using products from NXP's RoadLINK range to deliver in-car applications. Yoshitada Amagishi, Director, General Manager, Engineering HQ at ALPS Electric said: "ALPS Electric is committed to delivering enhanced

connected car technology to its customers. We have chosen to work with NXP and Cohda for its application ready C2X solution, based on its leading performance, flexibility and scalability, and its ability to address various use cases and OEM requirements."

"As the industry-leader in C2X communication, our chips enable OEMs to utilise a unique software-defined radio approach, to deploy global solutions based on a single hardware platform with end-of-line configurability," said Thomas Hinz, senior product marketing manager, RoadLINK, NXP Semiconductors. "We are launching the best performing C2X solutions in the market. It's the only solution that has been field proven in simTD and Safety Pilot, and which easily exceeds all of emerging Car-to-Car minimum performance requirements. It's fast, it works over extended distances and it has the features to fully realise the potential of C2X technology.

"NXP is dedicated to developing leading performance solutions to connect the car securely, improving road safety, reducing traffic congestion, ultimately creating smarter transport infrastructure."

Key Features of the TEF510x

- RF-Transceiver for global C2X standards, covering Europe, US and Japan, as well as DSRC and Wi-Fi (802.11abgn) standards
- Support for various antenna configurations and diversity schemes
- Together with SAF510x enabling Best-in-class 802.11p reception performance and communication range for mobility use cases even in non-line-of-sight conditions
- AEC-Q100 qualification scheduled for 2015

Provided by NXP

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